

<b>Notice of Allowability</b>	<b>Application No.</b>	<b>Applicant(s)</b>	
	10/696,581	NOMA ET AL.	
	Examiner	Art Unit	
	Thanhha Pham	2813	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address--

All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. **THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS.** This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.

1.  This communication is responsive to 12/13/2005.
2.  The allowed claim(s) is/are 1-15 and 20-23.
3.  Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
  - a)  All
  - b)  Some\*
  - c)  None
  1.  Certified copies of the priority documents have been received.
  2.  Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  3.  Copies of the certified copies of the priority documents have been received in this national stage application from the International Bureau (PCT Rule 17.2(a)).

\* Certified copies not received: \_\_\_\_\_.

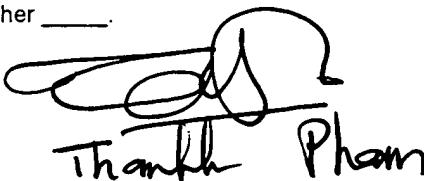
Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application.  
**THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.**

4.  A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.
5.  CORRECTED DRAWINGS ( as "replacement sheets") must be submitted.
  - (a)  including changes required by the Notice of Draftsperson's Patent Drawing Review ( PTO-948) attached
    - 1)  hereto or 2)  to Paper No./Mail Date \_\_\_\_\_.
  - (b)  including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No./Mail Date \_\_\_\_\_.

Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d).
6.  DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL.

#### Attachment(s)

1.  Notice of References Cited (PTO-892)
2.  Notice of Draftsperson's Patent Drawing Review (PTO-948)
3.  Information Disclosure Statements (PTO-1449 or PTO/SB/08),  
Paper No./Mail Date 12/13/2005
4.  Examiner's Comment Regarding Requirement for Deposit  
of Biological Material
5.  Notice of Informal Patent Application (PTO-152)
6.  Interview Summary (PTO-413),  
Paper No./Mail Date \_\_\_\_\_.
7.  Examiner's Amendment/Comment
8.  Examiner's Statement of Reasons for Allowance
9.  Other \_\_\_\_\_.



Thanhha Pham

***Status of claims***

1. Claims 16-18 have been cancelled according to Applicant's Amendment dated 06/24/2005.
2. Claim 19 was cancelled according to Examiner's Amendment dated 09/13/2005.
3. Claims 1-15 and 20-23 are allowed.

***Allowable Subject Matter***

4. The following is an examiner's statement of reasons for allowance:
  - Recorded Prior Art fails to disclose or suggest the combination of the process steps of manufacturing a semiconductor device as recited in the base claims 1 and 11 including: forming a second wiring connected to the exposed portion of the first wiring and extending over the surface of the second supporting substrate; forming a protection film on a surface of the second wiring by spray coating; and forming an opening in the protection film at a predetermined position to expose the second wiring.
  - Recorded Prior Art fails to disclose or suggest the combination of the process steps of manufacturing a semiconductor device as recited in the base claim 2 including: forming a cushioning portion on the second support of the substrate by spray coating; forming a second wiring connected to the exposed portion of the first wiring and extending over the surface of the second supporting substrate and the cushioning portion; forming a protection film on a surface of the second wiring by spray coating; and forming an opening in the protection film at a predetermined position to expose the second wiring.

Art Unit: 2813

- ▶ Recorded Prior Art also fails to disclose or suggest the combination of the process steps of manufacturing a semiconductor device as recited in the base claim 5: including forming a second wiring connected to the exposed portion of the first wiring and extending over the back surface of the semiconductor wafer; forming a protection film on a surface of the second wiring by spray coating; forming an opening in the protection film at a predetermined position to expose the second wiring.
- ▶ Recorded Prior Art also fails to disclose or suggest the combination of the process steps of manufacturing a semiconductor device as recited in the base claim 6 including: forming a cushioning portion on the back surface of the semiconductor wafer by spray coating; forming a second wiring connected to the exposed portion of the first wiring and extending over the back surface of the semiconductor wafer and the cushioning portion; forming a protection film on a surface of the second wiring; forming an opening in the protection film at a predetermined position to expose the second wiring.
- ▶ Recorded Prior Art also fails to disclose or suggest the combination of the process steps of manufacturing a semiconductor device as recited in the base claim 12 including: forming a cushioning portion on the second support substrate by spray coating; forming a second wiring connected to the exposed portion of the first wiring and extending over the back surface of second supporting substrate and the cushioning portion; forming a protection film on a surface of the second wiring by spray coating; forming an opening in the protection film at a predetermined position to expose the second wiring.

Art Unit: 2813

5. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thanhha Pham whose telephone number is (571) 272-1696. The examiner can normally be reached on Monday and Thursday 9:00AM - 9:30PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



Thanhha Pham